

LEADFRAME PACKAGE WITH DUMMY CHIP

Abstract of the Disclosure

5       The lead frame package with dummy chip comprising  
a lead frame with a plurality of first leads, molding  
compound, a dummy chip and a die. Wherein the molding  
compound encapsulates the die and the dummy chip, the  
dummy chip is arranged on a lower portion of the  
10 molding compound. The die is stacked on an upper  
surface of the dummy chip by using an adhesive  
material. A plurality of bonding wires are connected  
between the die and an end of the plurality of leads  
over the dummy chip.

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